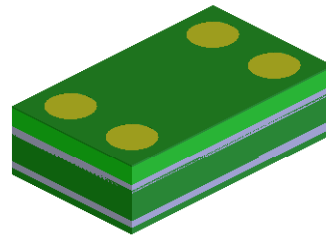
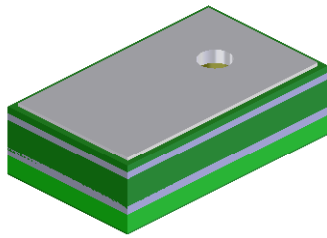


"Slim UltraMini" SiSonic™ Microphone Specification
With Enhanced RF Protection - *Halogen Free*



Knowles Acoustics
1151 Maplewood Drive
Itasca, IL 60143

1. DESCRIPTION AND APPLICATION

1.1 DESCRIPTION

"Slim UltraMini" Surface Mount Silicon Microphone
with Enhanced RF Protection - *Halogen Free*

1.2 APPLICATION

Consumer electronics devices

2. PART MARKING

Identification Number Convention

S 1 2 3

4 5 6 7

S: Manufacturing Location

"S" - Knowles Electronics Suzhou
Suzhou, China

"No Alpha Character" - Knowles Electronics
Itasca, IL USA

"E" - Engineering Samples

Digits 1-7: Job Identification Number

3. TEMPERATURE RANGE

3.1 Operating Temperature Range: -40°C to +100°C

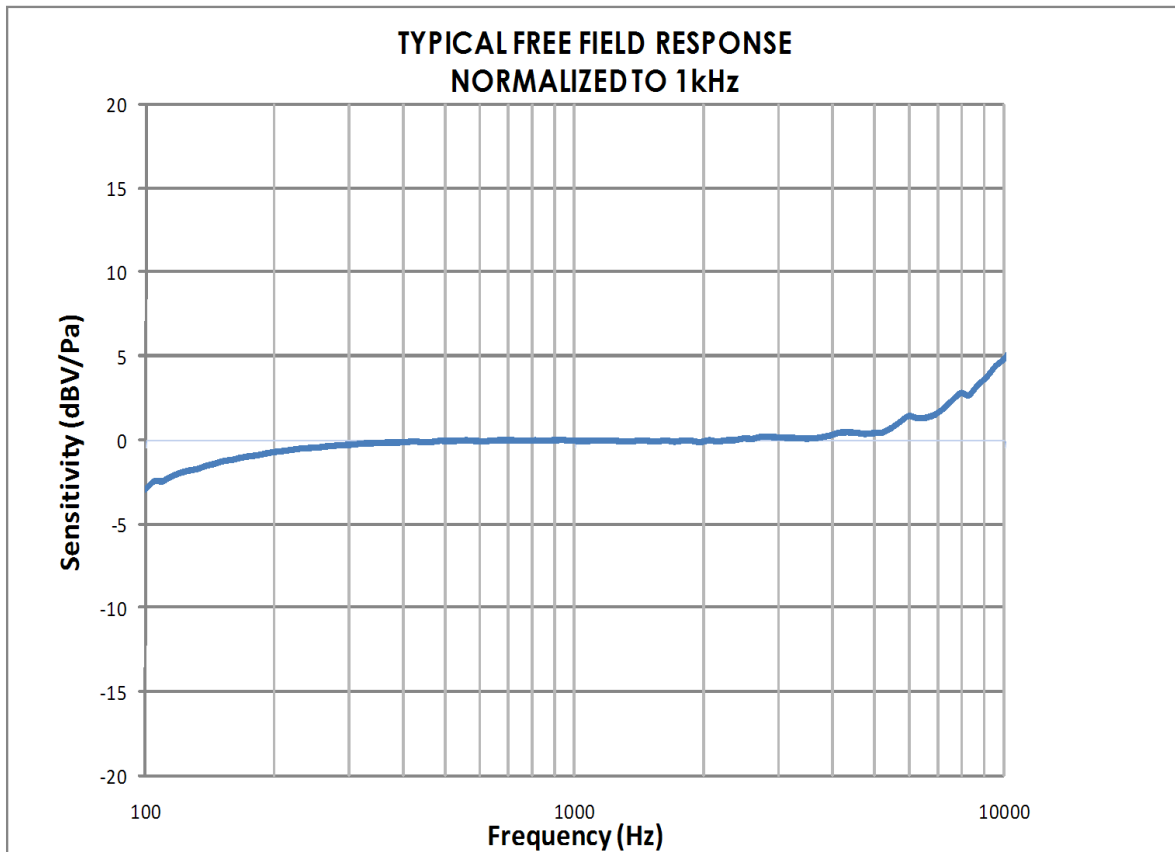
3.2 Storage Temperature Range: -40°C to +100°C

4. ACOUSTIC & ELECTRICAL SPECIFICATIONS

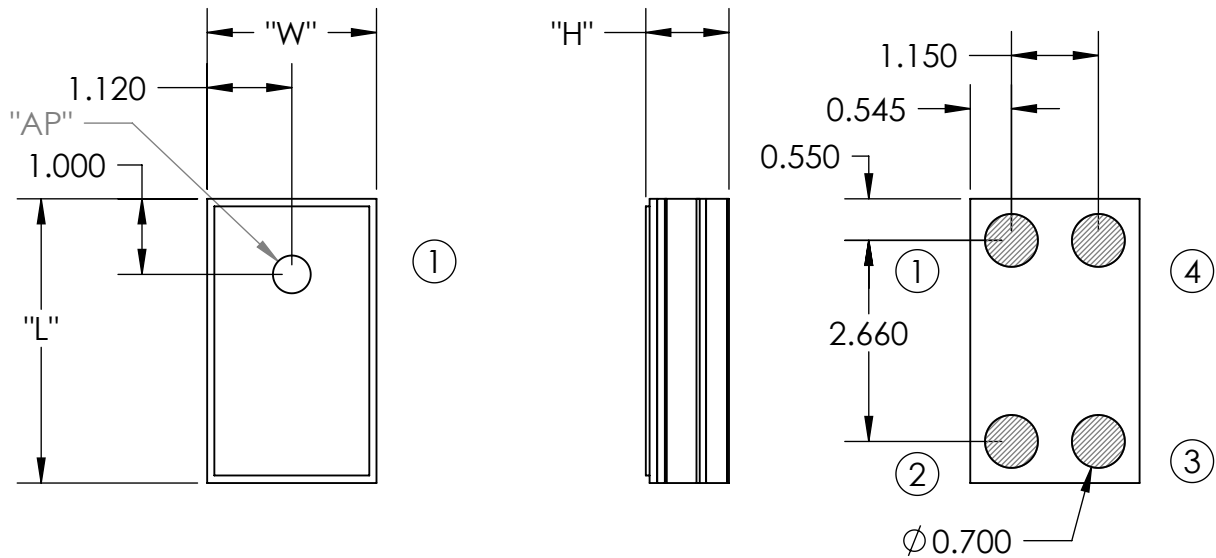
TEST CONDITIONS: +20 °C, 60-70% R.H.

	Symbol	Condition	Limits			Unit
			Min.	Nom.	Max.	
Directivity		Omni-directional	—	—	—	
Sensitivity	S	@ 1kHz (0dB-1V/Pa)	-45	-42	-39	dB
Output Impedance	Z _{OUT}	@ 1kHz (0dB-1V/Pa)	—	—	400	Ω
Current Consumption	I _{DDs}	Across 1.5 to 3.6 volts	—	—	250	μA
Signal to Noise Ratio	S/N	@ 1kHz (0dB-1V/Pa)	—	59	—	dB
Supply Voltage	V _s		1.5	—	3.6	V
Sensitivity Loss Across Voltage		Change in sensitivity over 3.6V to 1.5V	No Change Across Voltage Range			dB
Total Harmonic Distortion	THD	At 100dB SPL, THD < 1% At 150dB SPL, THD ≤ 10%				

5. FREQUENCY RESPONSE CURVE



6. MECHANICAL SPECIFICATIONS



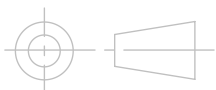
ITEM	DIMENSION	TOLERANCE	UNITS
LENGTH (L)	3.760	±0.100	mm
WIDTH (W)	2.240	±0.100	mm
HEIGHT (H)	1.100	±0.100	mm
ACOUSTIC PORT (AP)	Ø0.500	±0.100	mm

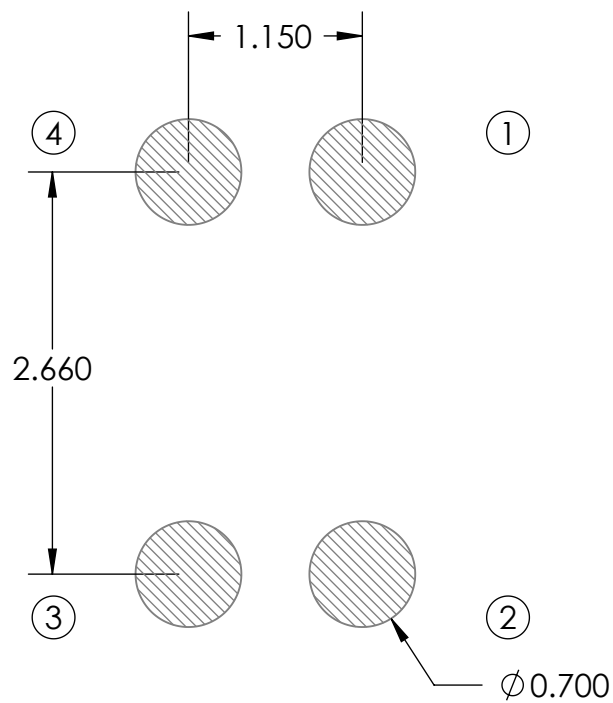
PIN OUTPUT	
PIN #	FUNCTION
1	POWER (Vdd)
2	GROUND
3	GROUND
4	OUTPUT

Note:

Dimensions are in millimeters unless otherwise specified.

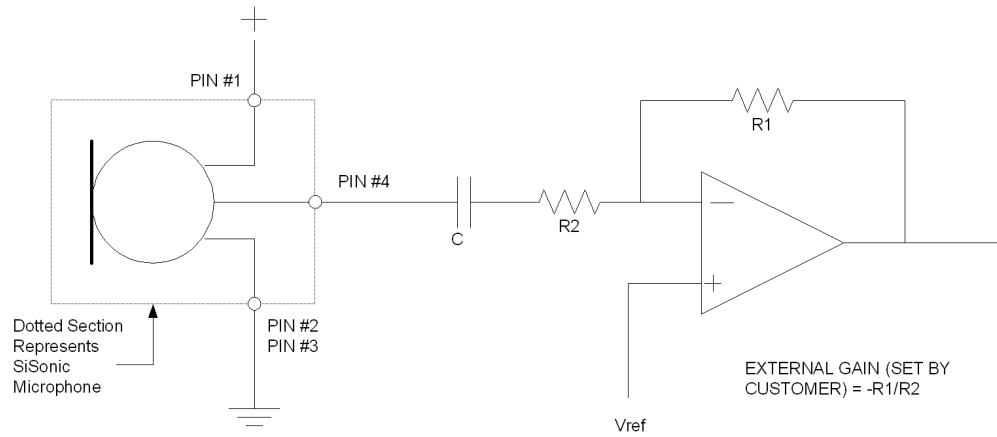
Tolerance ±0.15mm unless otherwise specified.

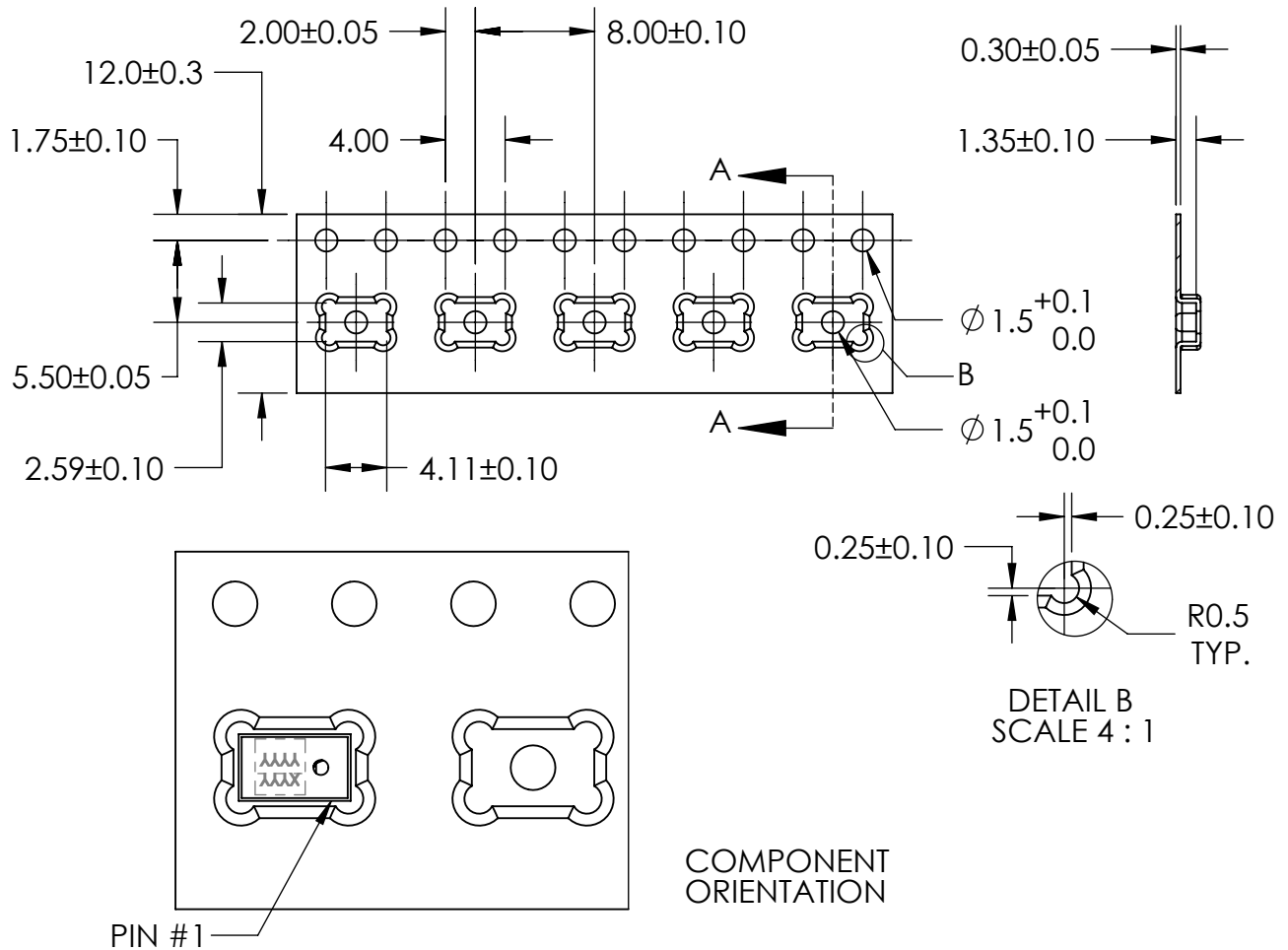


7. RECOMMENDED CUSTOMER LAND PATTERN**8. RECOMMENDED SOLDER STENCIL PATTERN**

N/A

9. RECOMMENDED INTERFACE CIRCUIT



10. PACKAGING DETAIL


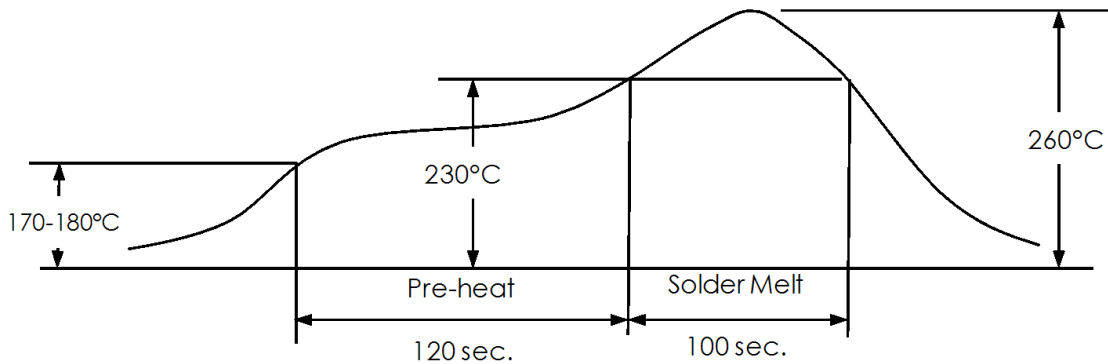
MODEL NUMBER	SUFFIX	REEL DIAMETER	QUANTITY PER REEL
SPQ0410HE5H-PB	-7	13"	5,700

TAPE & REEL	PER EIA-481
LABEL	LABEL APPLIED TO EXTERNAL PACKAGE & DIRECT TO REEL.

Note:

Dimensions are in millimeters unless otherwise specified.

11. SOLDER FLOW PROFILE



Stage	Temperature Profile	Time (maximim)
Pre-heat	170 ~ 180°C	120 sec.
Solder Melt	Above 230°C	100 sec.
Peak	260°C maximum	n/a

Notes:	
1.	<u>Do not pull a vacuum</u> over port hole of the microphone. Pulling a vacuum over the port hole can damage the device.
2.	<u>Do not board wash</u> after the reflow process. Board washing and cleaning agents can damage the device. Do not expose to ultrasonic processing or cleaning.
3.	<u>Do not brush board</u> after the reflow process. Brushing the board with/without solvents can damage the device.
4.	<u>Do not insert any object in port hole</u> of device at any time as this can damage the device.
5.	Number of reflow - Recommend no more than 3 cycles.

11. ADDITIONAL NOTES

- (A) Shelf life: Twelve (12) months when devices are to be stored in factory supplied, unopened ESD moisture sensitive bag under maximum environmental conditions of 30°C, 70% R.H.
- (B) MSL (moisture sensitivity level) Class 2a.

13. RELIABILITY SPECIFICATIONS

Note: After test conditions are performed, the sensitivity of the microphone shall not deviate more than 3dB from its initial value.

Test	Description
Thermal Shock	100 cycles of air-air thermal shock from -40°C to +125°C with 15 minute soaks. (ICE 68-2-4)
High Temperature Storage	+105°C environment for 1,000 hours. (ICE 68-2-2 Test Ba)
Low Temperature Storage	-40°C environment for 1,000 hours. (ICE 68-2-2 Test Aa)
High Temperature Bias	+105°C environment while under bias for 1,000 hours. (ICE 68-2-2 Test Ba)
Low Temperature Bias	-40°C environment while under bias for 1,000 hours. (ICE 68-2-2 Test Aa)
Temperature / Humidity Bias	+85°C/85% R.H. environment while under bias for 1,000 hours. (JESD22-A101A-B)
Vibration	4 cycles lasting 12 minutes from 20 TO 2,000 Hz in X, Y and Z direction with peak acceleration of 20g. (MIL 883E, Method 2007.2, A)
Electrostatic Discharge	3 discharges at +/-8kV direct contact to lid when unit is grounded (IEC 61000-4-2) and 3 discharges at +/-2kV direct contact to I/O pins. (MIL 883E, Method 3015.7)
Reflow	5 reflow cycles with peak temperature of +260°C.
Mechanical Shock	3 pulses of 10,000g in the X, Y and Z direction. (IEC 68-2-27, Test Ea)

